Power MOSFET, N-Channel, SUPERFET® III, FRFET®, 650 V, 65 A, 40 m Ω

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III FRFET MOSFET's optimized reverse recovery performance of body diode can remove additional component and improve system reliability.

Features

- 700 V @ T_J = 150°C
- Typ. $R_{DS(on)} = 32 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q_g = 158 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 1366 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Applications

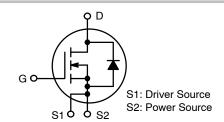
- Telecom / Server Power Supplies
- Industrial Power Supplies
- EV Charger
- UPS / Solar



ON Semiconductor®

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V _{DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	40 m $Ω$	65 A



POWER MOSFET



TO-247-4LD CASE 340CJ

MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Data Code (Year & Week) &K = Lot

NTH4L040N65S3F = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$, Unless otherwise noted)

Symbol	Parameter	Value	Unit		
V _{DSS}	Drain to Source Voltage	650	V		
V_{GSS}	Gate to Source Voltage	- DC	±30	V	
		- AC (f > 1 Hz)	±30		
I _D	Drain Current	– Continuous (T _C = 25°C)	65	Α	
		– Continuous (T _C = 100°C)	45		
I _{DM}	Drain Current	- Pulsed (Note 1)	162.5	Α	
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		1009	mJ	
I _{AS}	Avalanche Current (Note 2)		9	Α	
E _{AR}	Repetitive Avalanche Energy (Note 1)		4.46	mJ	
dv/dt	MOSFET dv/dt		100	V/ns	
	Peak Diode Recovery dv/dt (Note 3)		50		
P_{D}	Power Dissipation	(T _C = 25°C)	446	W	
		- Derate Above 25°C	3.57	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. Repetitive rating: pulse–width limited by maximum junction temperature.
2. $I_{AS} = 9 \text{ A}$, $R_G = 25 \Omega$, starting $T_J = 25^{\circ}\text{C}$.
3. $I_{SD} \leq 32.5 \text{ A}$, $di/dt \leq 200 \text{ A}/\mu\text{s}$, $V_{DD} \leq 400 \text{ V}$, starting $T_J = 25^{\circ}\text{C}$.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	0.28	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTH4L040N65S3F	NTH4L040N65S3F	TO-247 A04	Tube	N/A	N/A	30 Units

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
OFF CHARACT	ERISTICS		•	1	•	
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	650			V
		V _{GS} = 0 V, I _D = 1 mA, T _J = 150°C	700			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 15 mA, Referenced to 25°C		0.63		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V			10	μΑ
		V _{DS} = 520 V, T _C = 125°C		213		
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±30 V, V _{DS} = 0 V			±100	nA
N CHARACTE	ERISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 2.1$ mA	3.0		5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 32.5 A		32	40	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 20 V, I _D = 32.5 A		48		S
YNAMIC CHA	RACTERISTICS					
C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0 V, f = 1 MHz		5940		pF
C _{oss}	Output Capacitance			140		pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		1366		pF
C _{oss(er.)}	Energy Related Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		247		pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 400 V, I _D = 32.5 A, V _{GS} = 10 V (Note 4)		158		nC
Q _{gs}	Gate to Source Gate Charge			48		nC
Q _{gd}	Gate to Drain "Miller" Charge			60		nC
ESR	Equivalent Series Resistance	f = 1 MHz		1.1		Ω
WITCHING CH	HARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 400 V, I _D = 32.5 A,		44		ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, R_g = 2.2 \Omega$ (Note 4)		23		ns
t _{d(off)}	Turn-Off Delay Time			96		ns
t _f	Turn-Off Fall Time			6		ns
OURCE-DRAI	N DIODE CHARACTERISTICS		•	1		
I _S	Maximum Continuous Source to Drain Diode Forward Current				65	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current				162.5	Α
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 32.5 A			1.3	V
t _{rr}	Reverse Recovery Time	V _{DD} = 400 V, I _{SD} = 32.5 A,		145		ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/μs		737		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

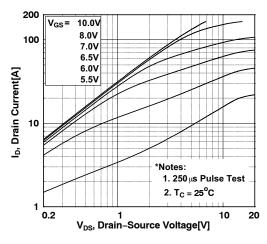


Figure 1. On-Region Characteristics

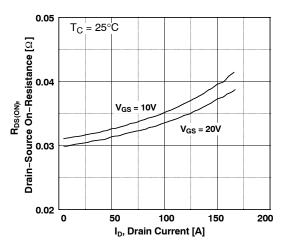


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

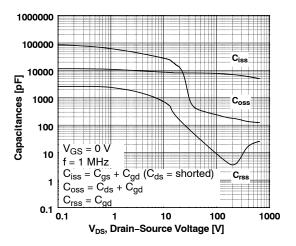


Figure 5. Capacitance Characteristics

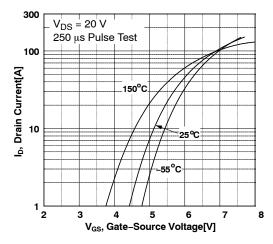


Figure 2. Transfer Characteristics

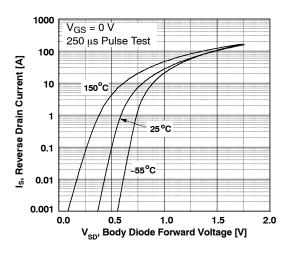


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

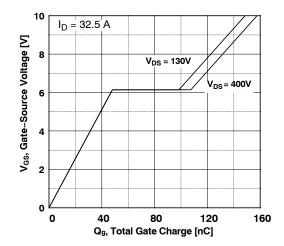


Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS

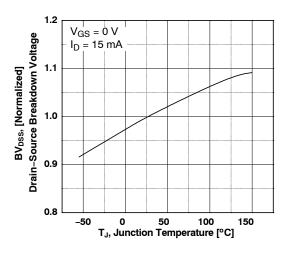


Figure 7. Breakdown Voltage Variation vs. Temperature

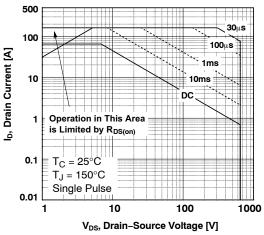


Figure 9. Maximum Safe Operating Area

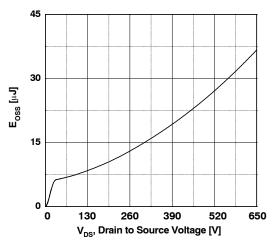


Figure 11. Eoss vs. Drain to Source Voltage

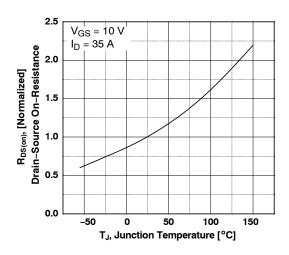


Figure 8. On–Resistance Variation vs. Temperature

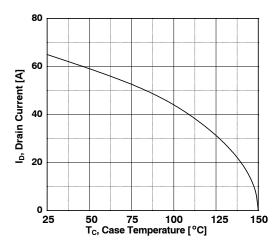


Figure 10. Maximum Drain Current vs. Case Temperature

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

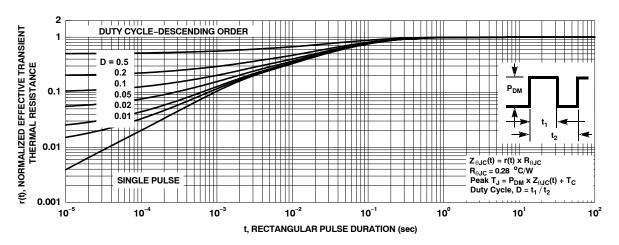


Figure 12. Transient Thermal Response Curve

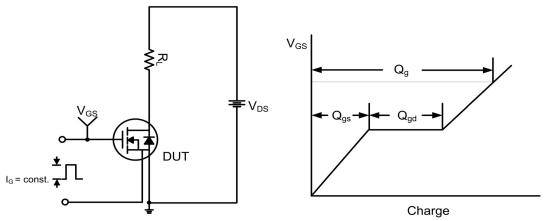


Figure 13. Gate Charge Test Circuit & Waveform

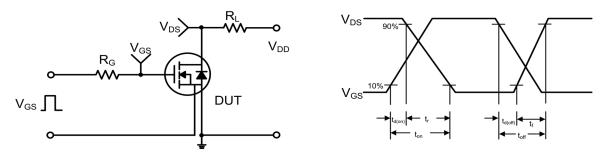


Figure 14. Resistive Switching Test Circuit & Waveforms

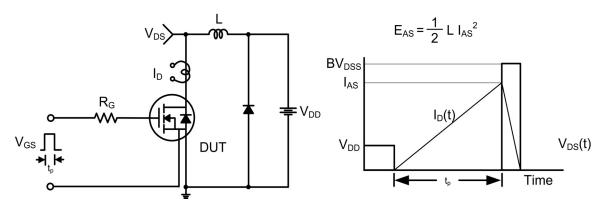


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

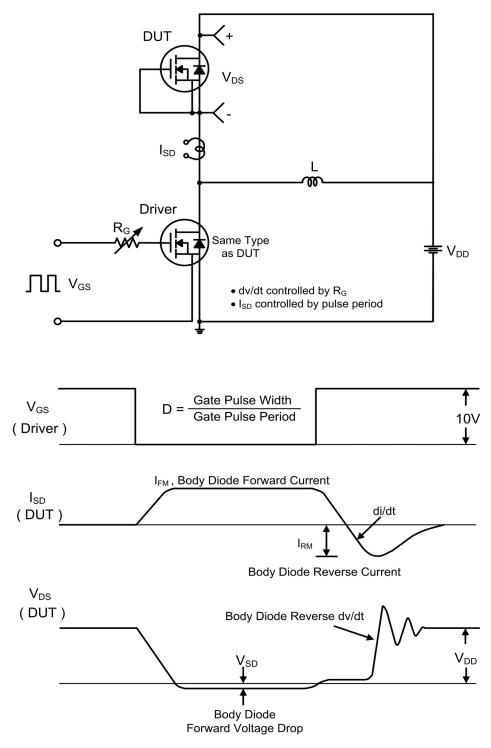
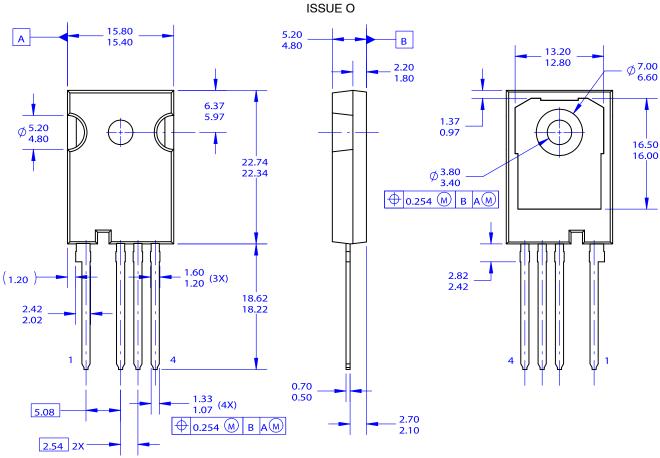


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

PACKAGE DIMENSIONS

TO-247-4LDCASE 340CJ



NOTES:

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DRAWING CONFORMS TO ASME Y14.5-2009.

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